



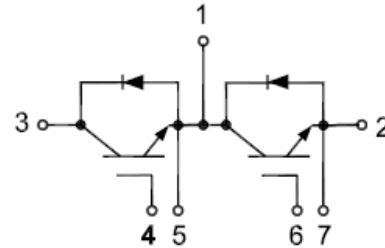
GK200HF60T1VH

IGBT Module

Preliminary Data

Features:

- Non Punch Through (NPT) Technology
- Short Circuit Rated > 10 μ s
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested (2 \times I_c)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement



Applications:

- Welding Machine、Cutting Machine
- Plating Power Supply、Induction Heating
- SMPS、UPS

IGBT, Inverter

Maximum Rated Values (T_C=25°C unless otherwise specified)

V _{CES}	Collector-Emitter Blocking Voltage		600	V
V _{GES}	Gate-Emitter Voltage		±20	V
I _C	Continuous Collector Current	T _C =80°C	200	A
		T _C =25°C	235	A
I _{CM}	Repetitive Peak Collector Current	t _p =1ms	400	A
t _{SC}	Short Circuit Withstand Time		>10	μs
P _D	Maximum Power Dissipation per IGBT	T _C =25°C T _{Jmax} =150°C	933	W



Electrical Characteristics of IGBT ($T_C=25^\circ\text{C}$ unless otherwise specified)

Static Characteristics

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=8\text{mA}$, $V_{CE}=V_{GE}$, $T_J=25^\circ\text{C}$	4.0	5.0	5.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=200\text{A}$, $V_{GE}=15\text{V}$	$T_J=25^\circ\text{C}$	2.10	2.40	V
			$T_J=125^\circ\text{C}$	2.30		V
I_{CES}	Collector-Emitter Leakage Current	$V_{GE}=0\text{V}$, $V_{CE}=V_{CES}$, $T_J=25^\circ\text{C}$			1	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}$, $V_{CE}=0\text{V}$, $T_J=25^\circ\text{C}$			200	nA
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$, $f=100\text{kHz}$, $T_J=25^\circ\text{C}$		7.52		nF
C_{oes}	Output Capacitance			1.19		nF
C_{res}	Reverse Transfer Capacitance			0.75		nF

Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=300\text{V}$, $I_C=200\text{A}$, $R_{Gon}=29\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^\circ\text{C}$	838		ns
			$T_J=125^\circ\text{C}$	584		
t_r	Rise Time		$T_J=25^\circ\text{C}$	207		ns
			$T_J=125^\circ\text{C}$	289		
$t_{d(off)}$	Turn-off Delay Time	$V_{CC}=300\text{V}$, $I_C=200\text{A}$, $R_{Goff}=29\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^\circ\text{C}$	1045		ns
			$T_J=125^\circ\text{C}$	1020		
t_f	Fall Time		$T_J=25^\circ\text{C}$	115		ns
			$T_J=125^\circ\text{C}$	109		
E_{on}	Turn-on Switching Loss	$V_{CC}=300\text{V}$, $I_C=200\text{A}$, $R_{Gon}=29\Omega$, $V_{GE}=\pm 15\text{V}$, $di/dt=610\text{A}/\mu\text{s}$ ($T_J=125^\circ\text{C}$) Inductive Load	$T_J=25^\circ\text{C}$	5.76		mJ
			$T_J=125^\circ\text{C}$	9.30		
E_{off}	Turn-off Switching Loss		$T_J=25^\circ\text{C}$	10.82		mJ
			$T_J=125^\circ\text{C}$	11.79		
Q_g	Total Gate Charge	$V_{GE}=+15\text{V}\dots-15\text{V}$	$T_J=25^\circ\text{C}$	1.13		μC
R_G	Internal Gate Resistance		$T_J=25^\circ\text{C}$	2.35		Ω
RBSOA	$I_C=400\text{A}$, $V_{CC}=480\text{V}$, $V_p=600\text{V}$, $R_G=29\Omega$, $V_{GE}=+15\text{V}$ to 0V , $T_J=150^\circ\text{C}$			Trapezoid		
SCSOA	$V_{CC}=300\text{V}$, $V_{GE}=15\text{V}$, $T_J=150^\circ\text{C}$			10		μs
$R_{\theta JC}$	IGBT Thermal Resistance: Junction-To-Case (per IGBT)				0.134	$^\circ\text{C}/\text{W}$



Diode, Inverter

Maximum Rated Values ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

V_{RRM}	Repetitive Peak Reverse Voltage	600	V
I_F	Diode Continuous Forward Current	200	A
I_{FM}	Diode Maximum Forward Current	400	A

Electrical Characteristics of Diode ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

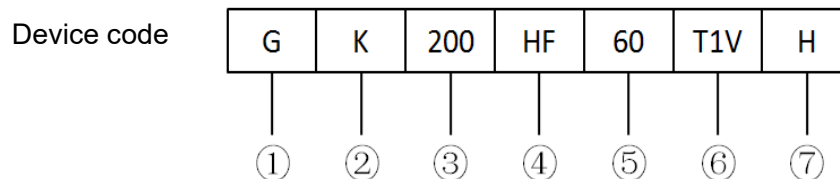
Symbol	Description	Conditions	Min.	Typ.	Max.	Units	
V_{FM}	Forward Voltage	$I_F=200\text{A}$	$T_J=25^{\circ}\text{C}$	1.70	2.00	V	
			$T_J=125^{\circ}\text{C}$	1.80			
t_{rr}	Reverse Recovery Time	$I_F=200\text{A}$, $-di_F/dt=780\text{A}/\mu\text{s}(T_J=125^{\circ}\text{C})$, $V_R=300\text{V}$, $V_{GE}=-15\text{V}$	$T_J=25^{\circ}\text{C}$	119		ns	
			$T_J=125^{\circ}\text{C}$	170			
I_{rr}	Peak Reverse Recovery Current		$T_J=25^{\circ}\text{C}$	48.4		A	
			$T_J=125^{\circ}\text{C}$	67.2			
Q_{rr}	Reverse Recovery Charge		$T_J=25^{\circ}\text{C}$	3.62		μC	
			$T_J=125^{\circ}\text{C}$	7.19			
E_{rec}	Reverse Recovery Energy		$T_J=25^{\circ}\text{C}$	0.33		mJ	
			$T_J=125^{\circ}\text{C}$	1.20			
$R_{\theta JC}$	Diode Thermal Resistance: Junction-To-Case (per Diode)				0.306	$^{\circ}\text{C}/\text{W}$	



Module

Symbol	Description	Min.	Typ.	Max.	Units
V _{iso}	Isolation Voltage (All Terminals Shorted) RMS, f=50Hz, 30s	4500			V
T _J	Maximum Junction Temperature			150	°C
T _{JOP}	Maximum Operating Junction Temperature Range	-40		+150	°C
T _{stg}	Storage Temperature	-40		+125	°C
CTI	Comparative Tracking Index	200			
R _{ecs}	Case-To-Sink Thermally (Conductive Grease Applied)			0.07	°C/W
T	Power Terminals Screw:M5	3.0		5.0	N·m
T	Mounting Screw:M6	4.0		6.0	N·m
G	Weight		165		g

Ordering Information Table



- ① - IGBT Module
- ② - Non Punch Through (NPT) Technology
- ③ - Rated Current (200=200A)
- ④ - Circuit Configuration (HF=Half Bridge)
- ⑤ - Rated Voltage (60=600V)
- ⑥ - Package Type
- ⑦ - Test Level (Pass the Important Reliability Test-Industrial Grade)

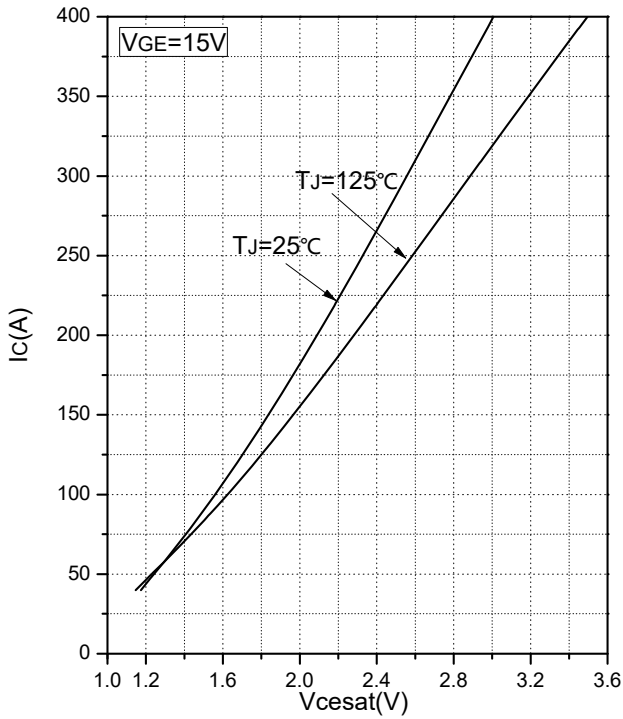


Fig.1 Typical Saturation Voltage Characteristics

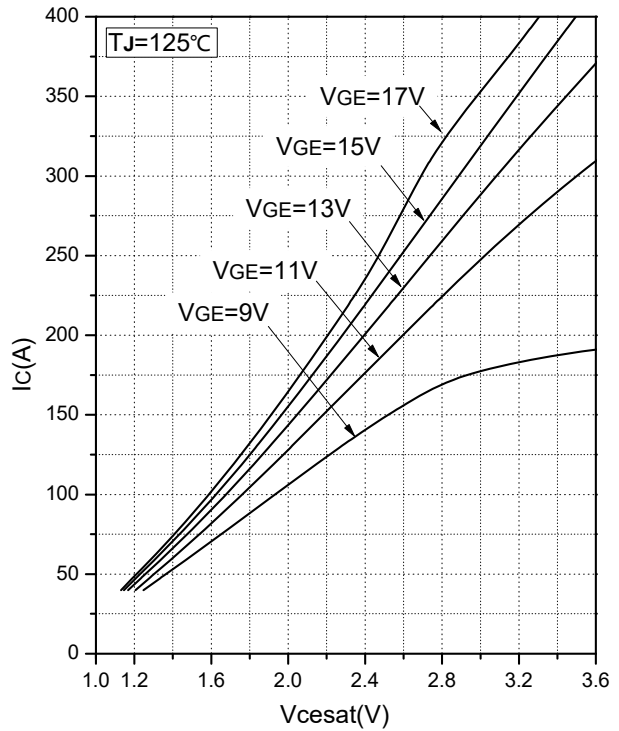


Fig.2 Typical Output Characteristics

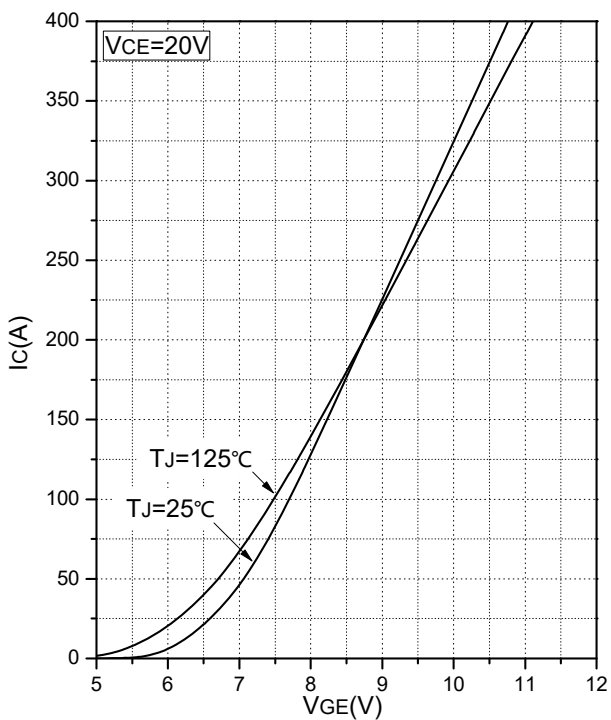


Fig.3 Transfer Characteristic

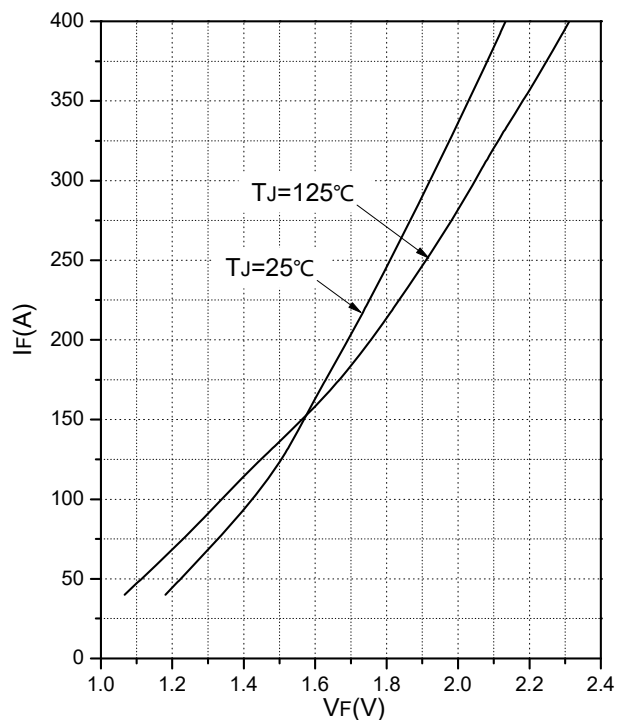


Fig.4 Forward Characteristics of Diode

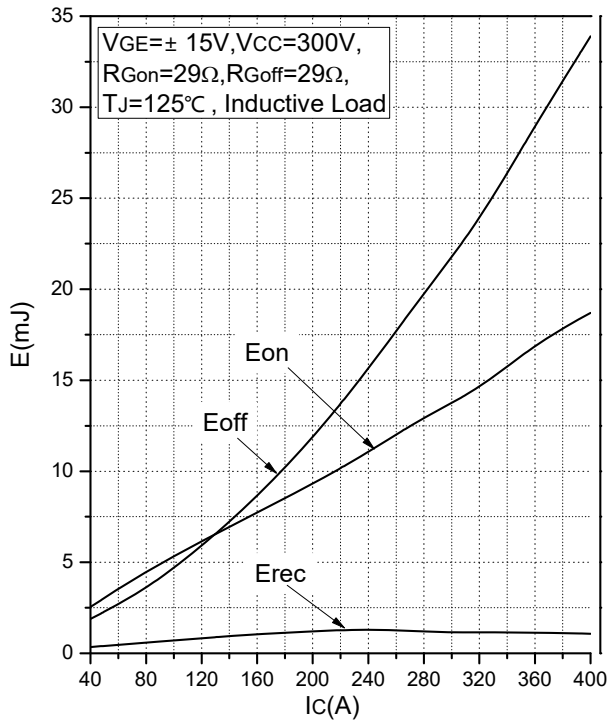


Fig.5 Typical Switching Loss vs. Collector Current

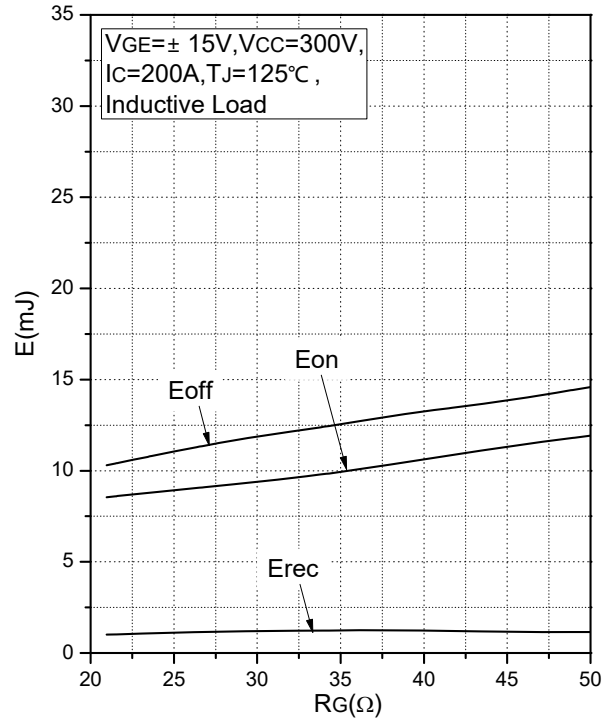


Fig.6 Typical Switching Loss vs. Gate Resistance

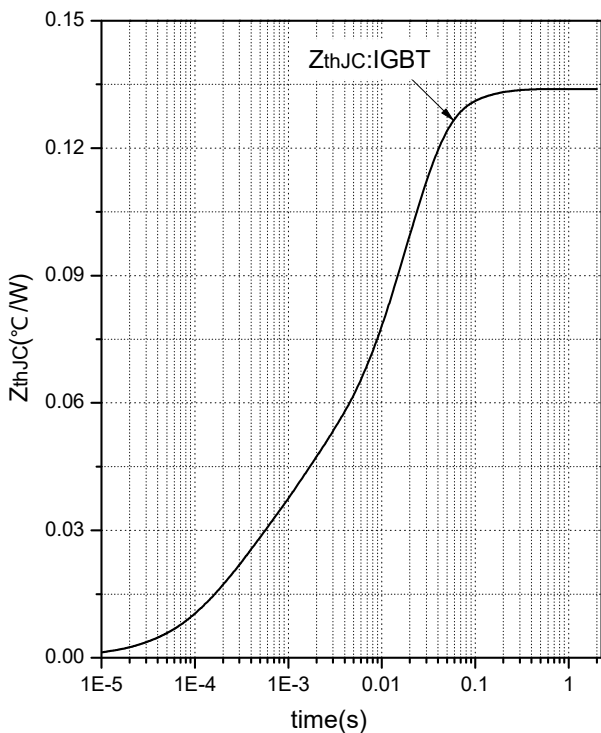


Fig.7 Transient Thermal Impedance (IGBT)

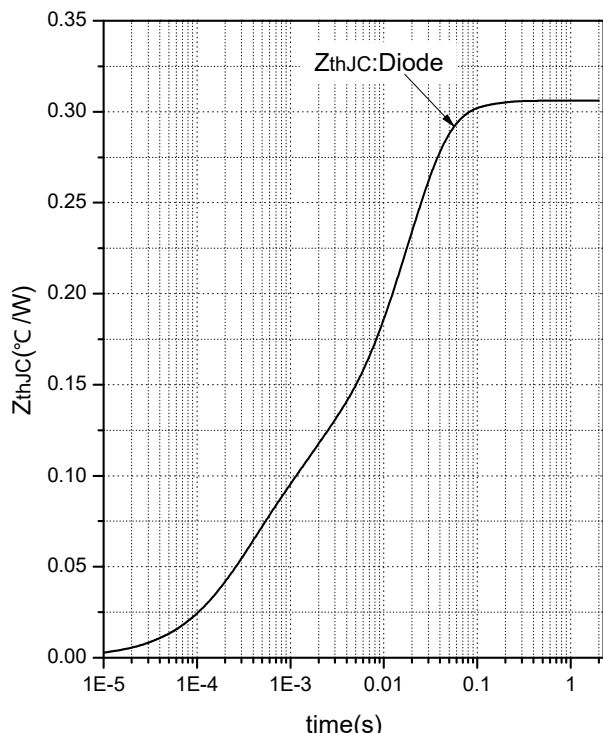


Fig.8 Transient Thermal Impedance (Diode)

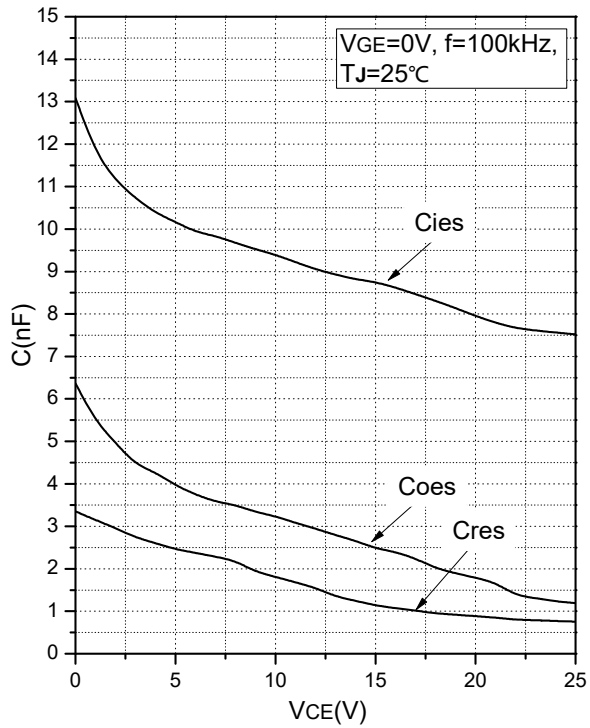


Fig.9 Capacitance Characteristics

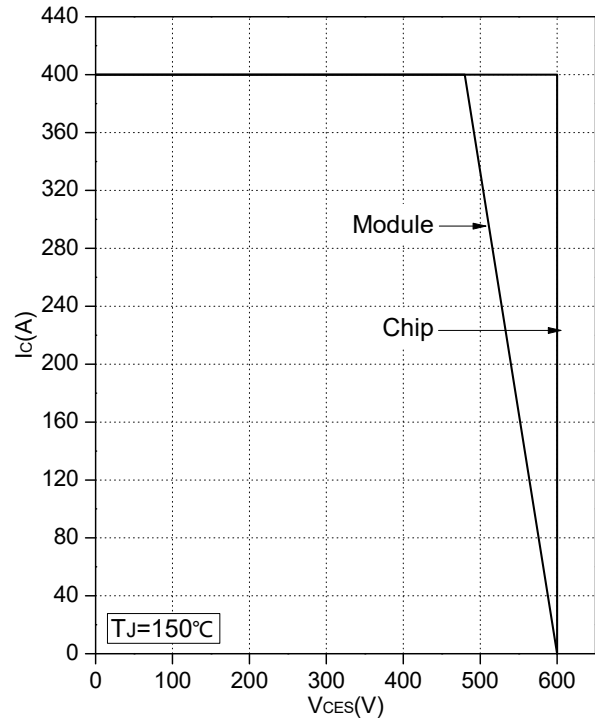
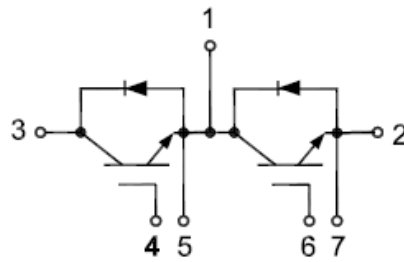


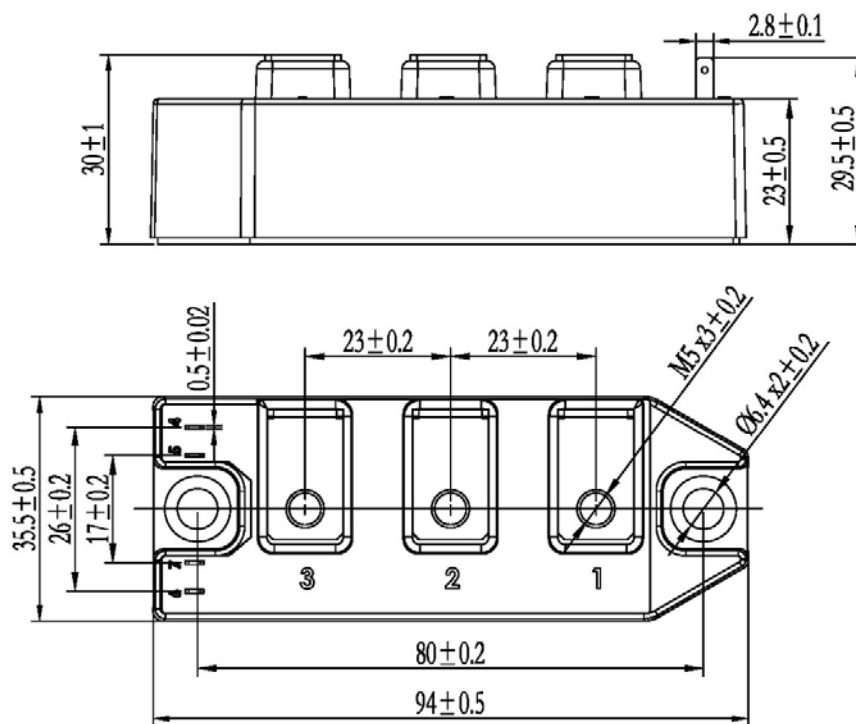
Fig.10 Reverse Bias Safe Operation Area (RBSOA)



Internal Circuit



Package Outline (Unit: mm):





Date	Revision	Notes
09/04/2023	01	Initial Release

Announcement

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The released datasheet would be issued with “REV.” + “alphabet characters”.